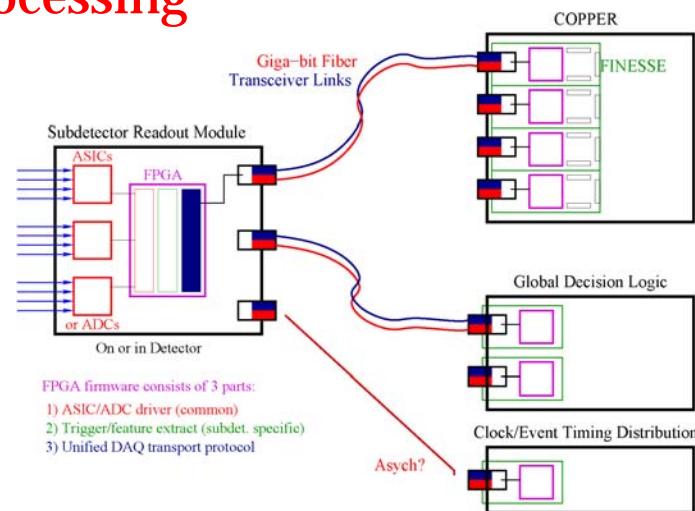


X-ray FEL Detector mechanics

- Overview
- Planned 1st run configuration
 - Flux estimates
 - Detector configuration
 - Data rates
- Future development efforts
 - Detectors
 - Electronics/processing



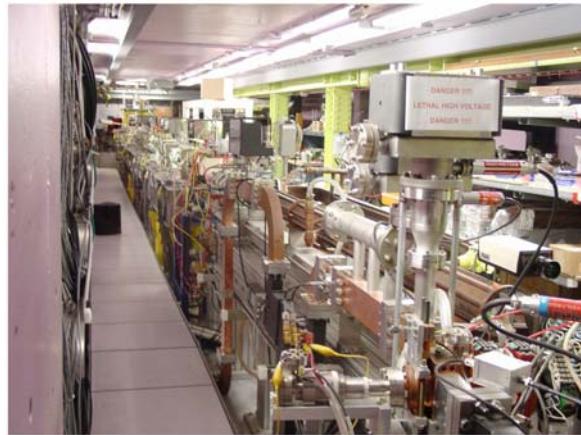
Juaquin Anderson
Matt Andrew
Michael Cooney
Xin Gao
James Kennedy
Luca Macchiarulo
Marc Rosen
Larry Ruckman
Gary Varner



5-FEB-2010

Bremsstrahlung Beamline Estimates

Dec.-2009



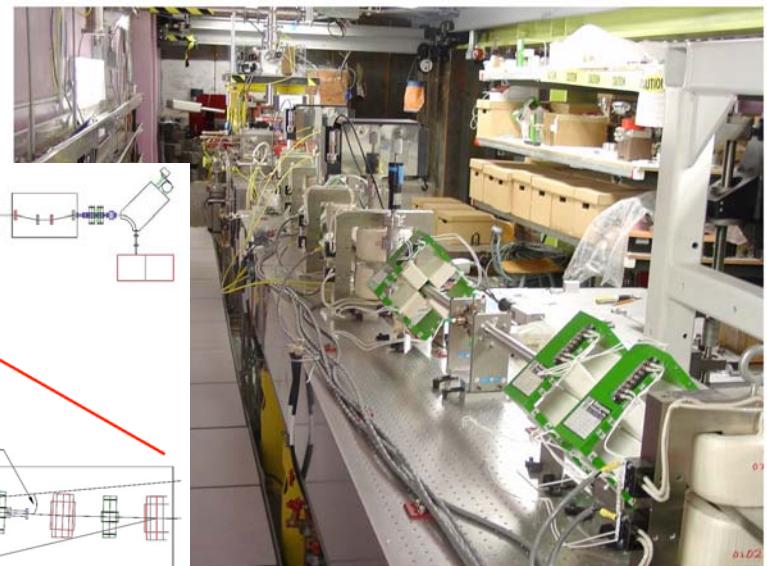
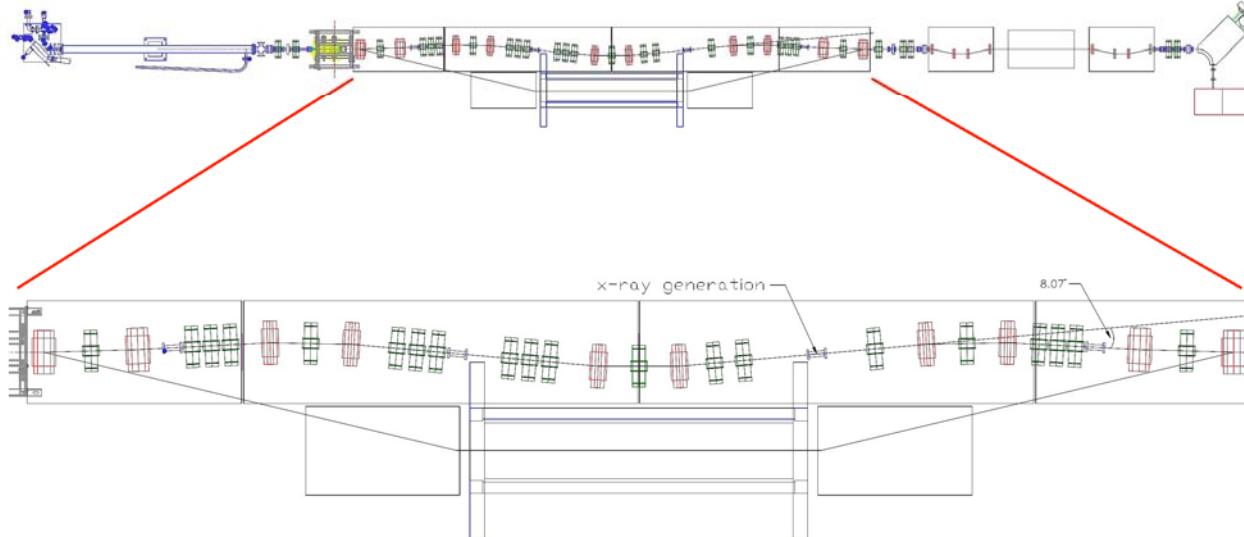
Target:
Thin
Cu foil
1 mil

Vacuum
Al Exit
Window
Air
~15"
5 mil

Helium filled bag/volume

10 mil polyethylene

Plastic cover
Active Si
Bulk Si
Carrier
FR-4 (PCB)
300 um
200 um
62.5 mil
1mm
????



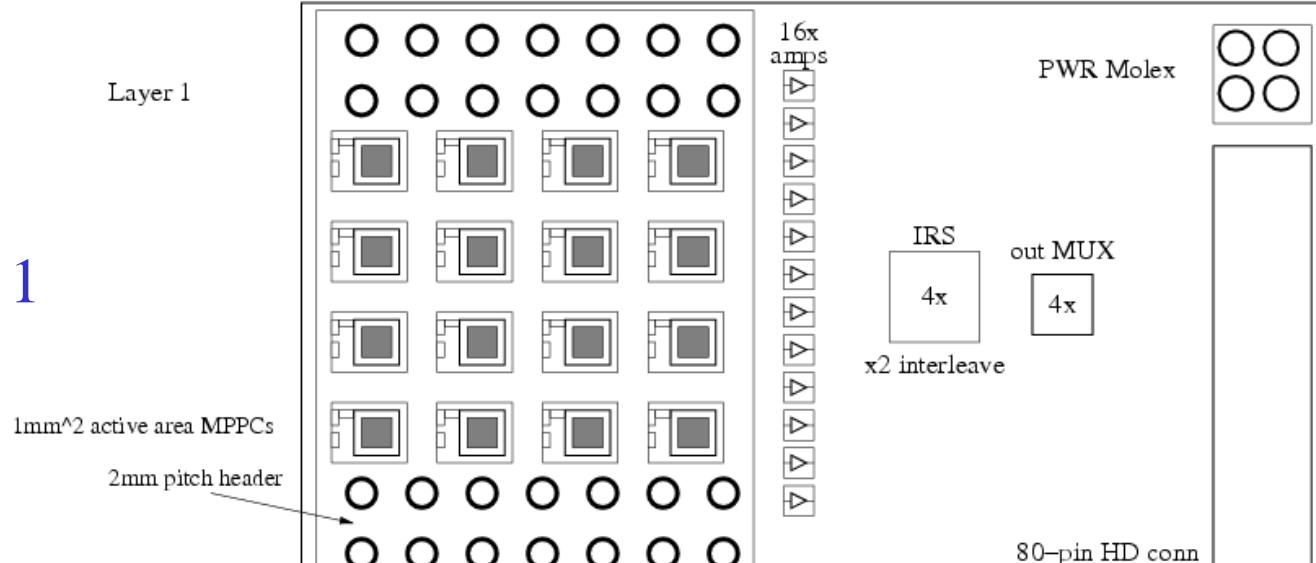
Brem beamline Summary

- Initial run with 2 detector planes
 - 1mm² array for “bare” layer
 - 3mm² array with BaF₂ radiator
- More than adequate flux (2nd layer)
- Developed x-ray transport simulation
 - Input to a signal Monte Carlo
 - Fix readout/ASIC design specifications

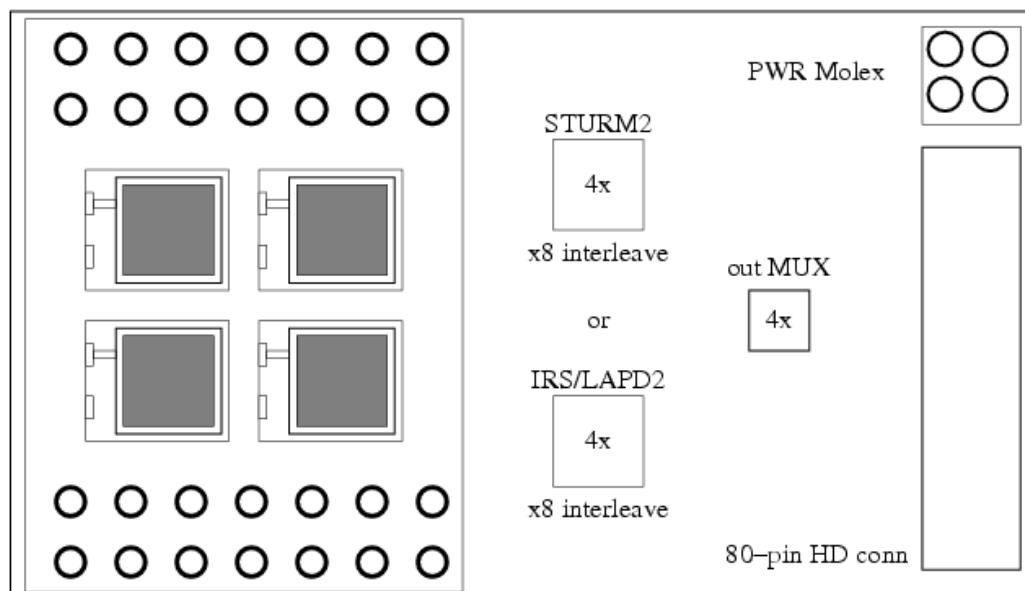
First Detector Arrays

First Generation FEL x-ray (TEDA) Readout

Layer 1

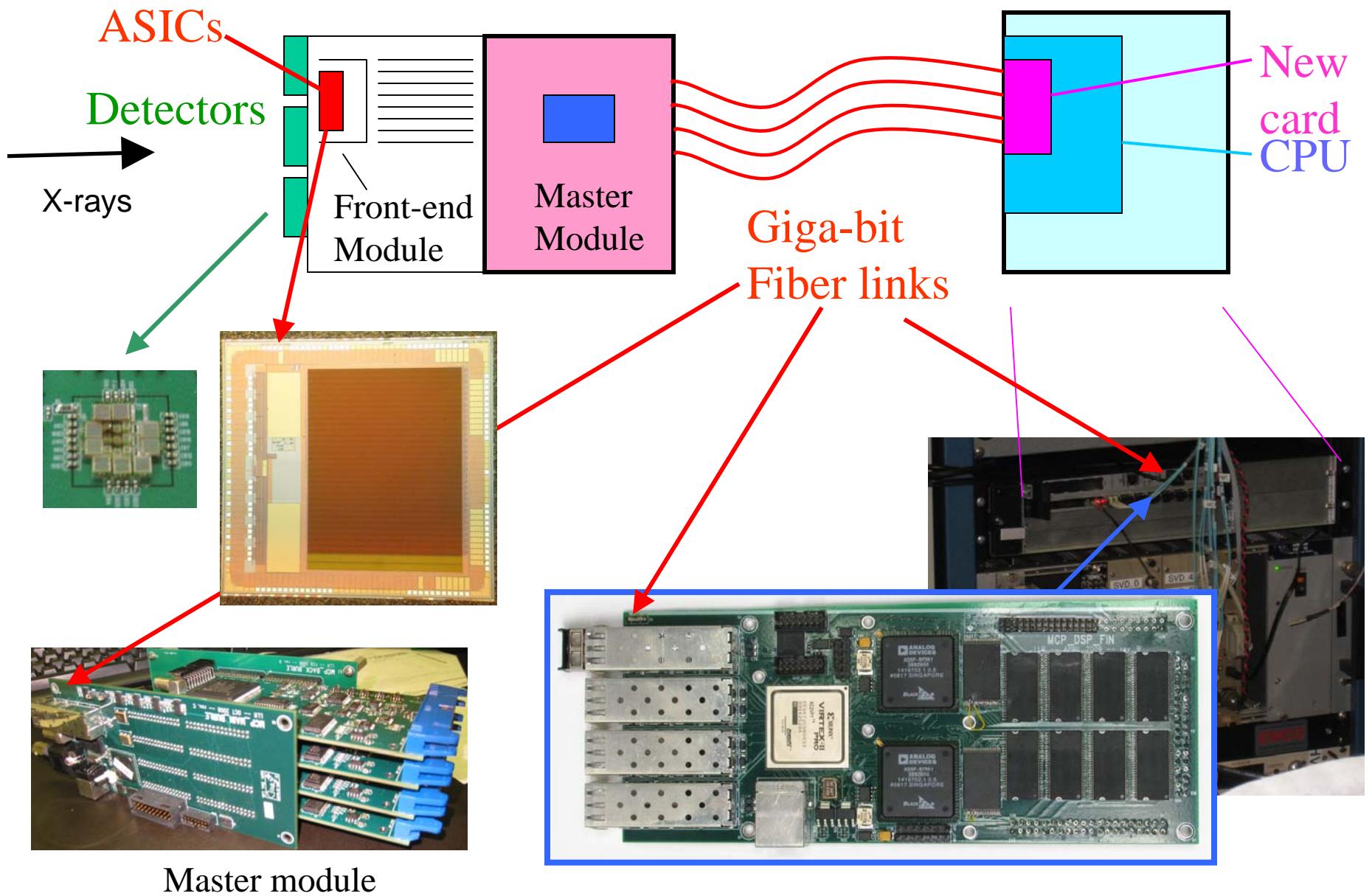


Layer 2



Readout for FEL x-ray beamline

cPCI crate (control room)



First Prototype throughput

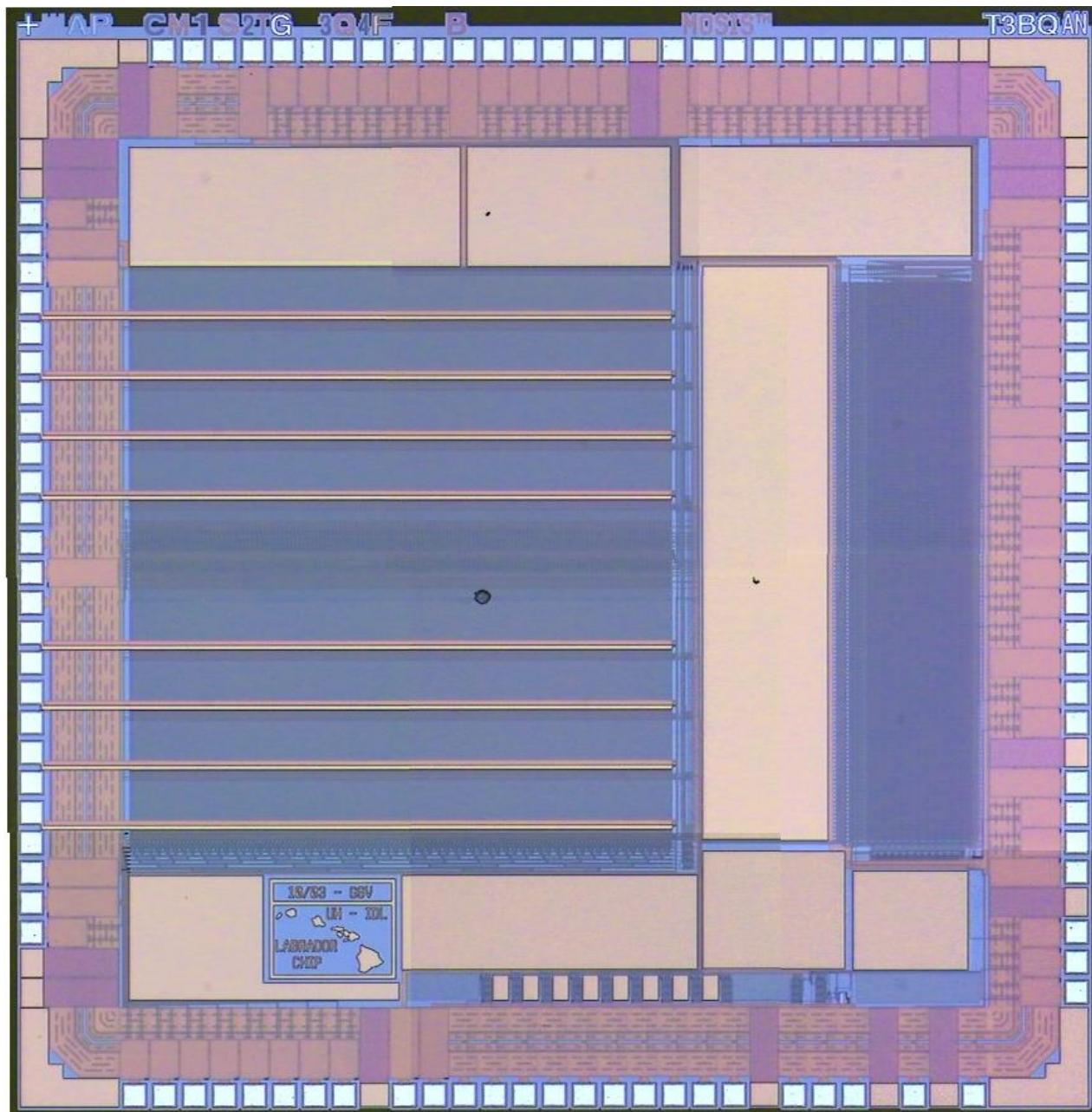
- For configuration shown earlier
 - 1 layer = 4 ASICs (8Ch.)
 - 1 “shot” = 4 chip * 8Ch * 32k = 1Msmp/layer
 - (1 shot = 8us recording @ 4GSa/s)
- 16Mbit/s/shot
- 320Mbit/s @ 20Hz operation
 - 2x Layers/fiber ~ 0.64 Gb/s (20% capacity)
 - May do 1 fiber/layer for convenience (fibers are inexpensive)
- 40MBytes/s raw data (need to feature extract)

Readout System Summary

Great Progress

- Now have a clear plan for late Feb. first run (on schedule)
- ASIC development path is multi-prong, design effort will intensify this semester
- Data transfer architecture has plenty of margin and is scaleable upward
- Detector development – prototype from CERN in February; further device fabrication runs

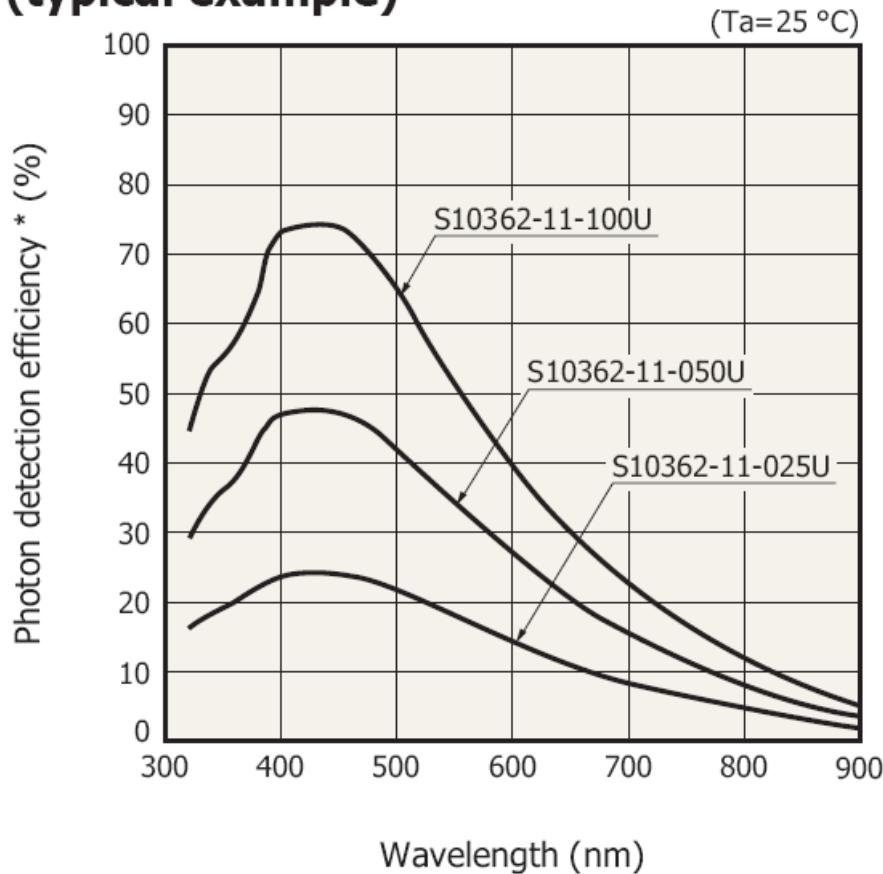
Back-up slides



1, 3 mm²

Hamamatsu MPPC

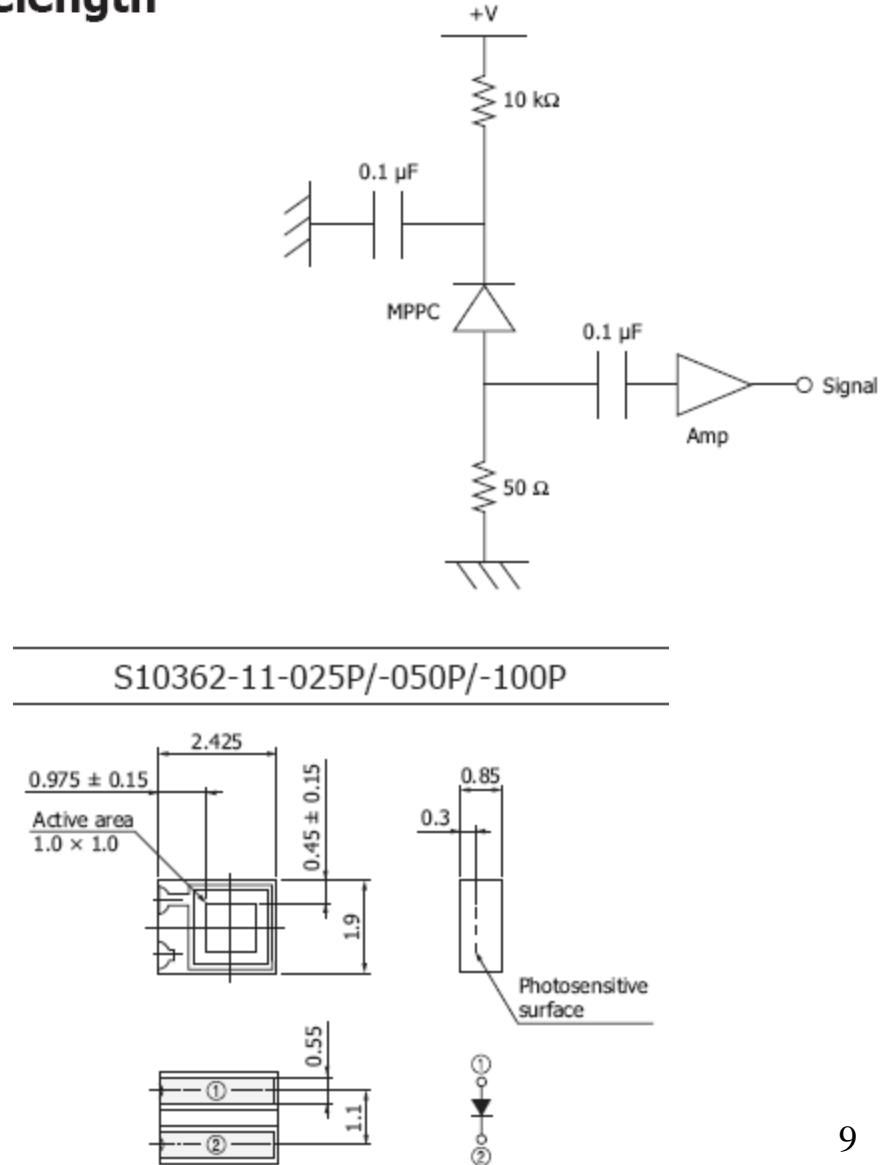
Photon detection efficiency (PDE) vs. wavelength (typical example)



* Photon detection efficiency includes effects of crosstalk and afterpulses.

Ordered 10x 1, 3 mm²

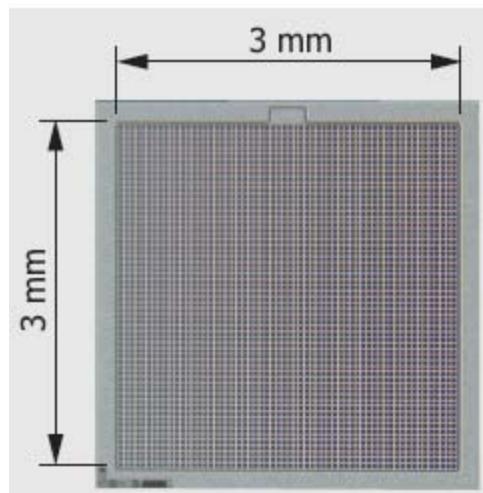
Connection example



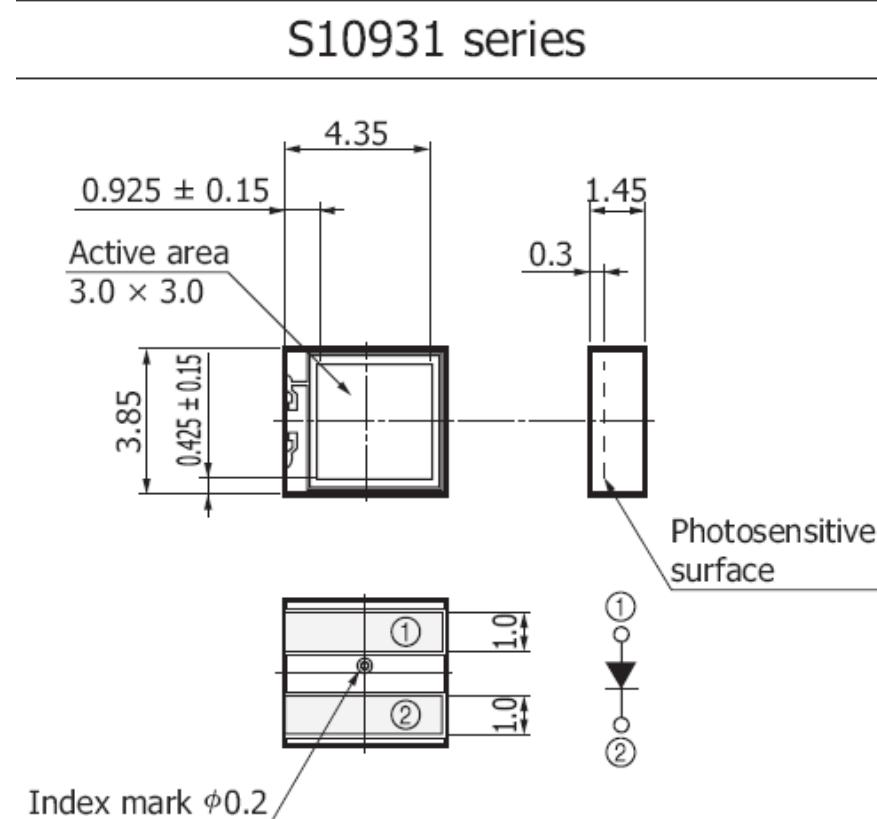
3 mm² Hamamatsu MPPC coverage



14,400 pixels
for the 25 μ m
pixel case



Better fill-factor
for tiling →
~53% active



$G = 2.7 \times 10^5$
TTS ~ 250ps RMS (single p.e.)

Proto ASIC psTDC1

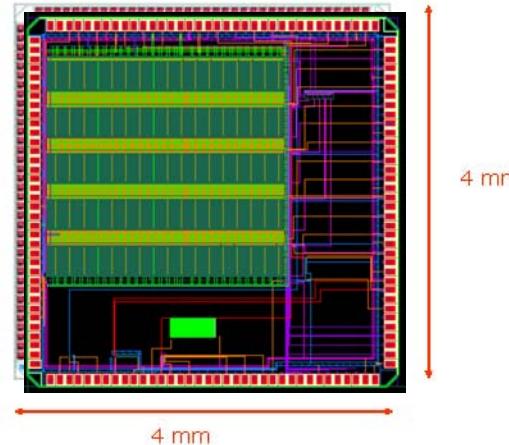
“oscilloscope on a chip”

Specifications

- 10-15 GSa/s
- >= 2GHz analog bandwidth
- 256 sample cells
- 4 channels
- separate timing channel
- on-chip conversion
- IBM 130nm CMOS process
- 25.6 μ s readout
- 40mW/channel
- Direct interface (stud-bond) to microstrip board

ASIC in evaluation

Chip Layout



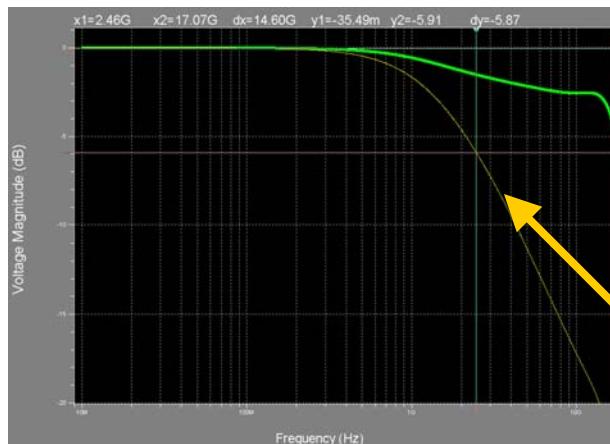
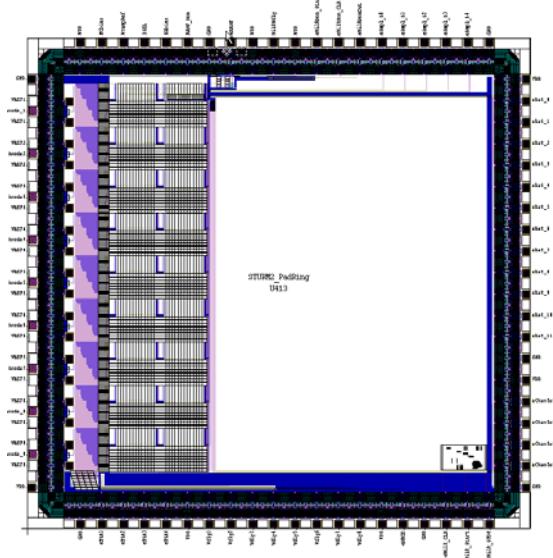
STURM2 Prototype (evol. Step)

“Max bandwidth/throughput”

Specifications

8	channels/STURM sampling
1	monitor channel
4	TSA sample buffers
8	samples/TSA buffer (32x channel)
288	Wilkinson conversion cells
1-200	GSa/s effective (5ps - 1ns Tstep)
1	word (RAM) sample readout
$1+n^*0.02$	us to read n samples
100	kHz sustained readout (orbit)

Chip Layout

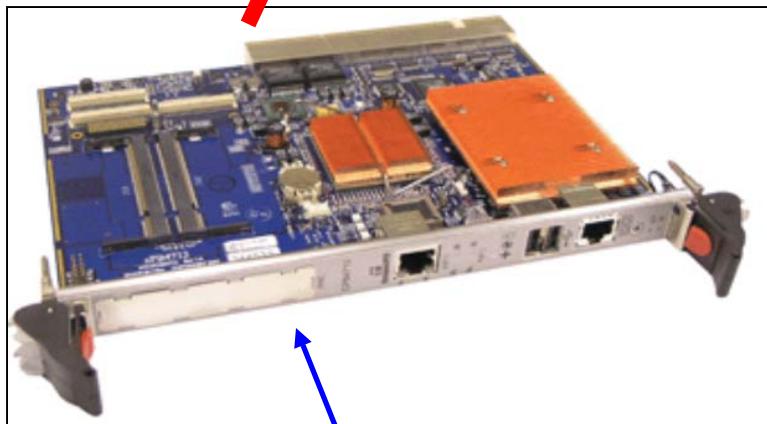


ASIC in fabrication

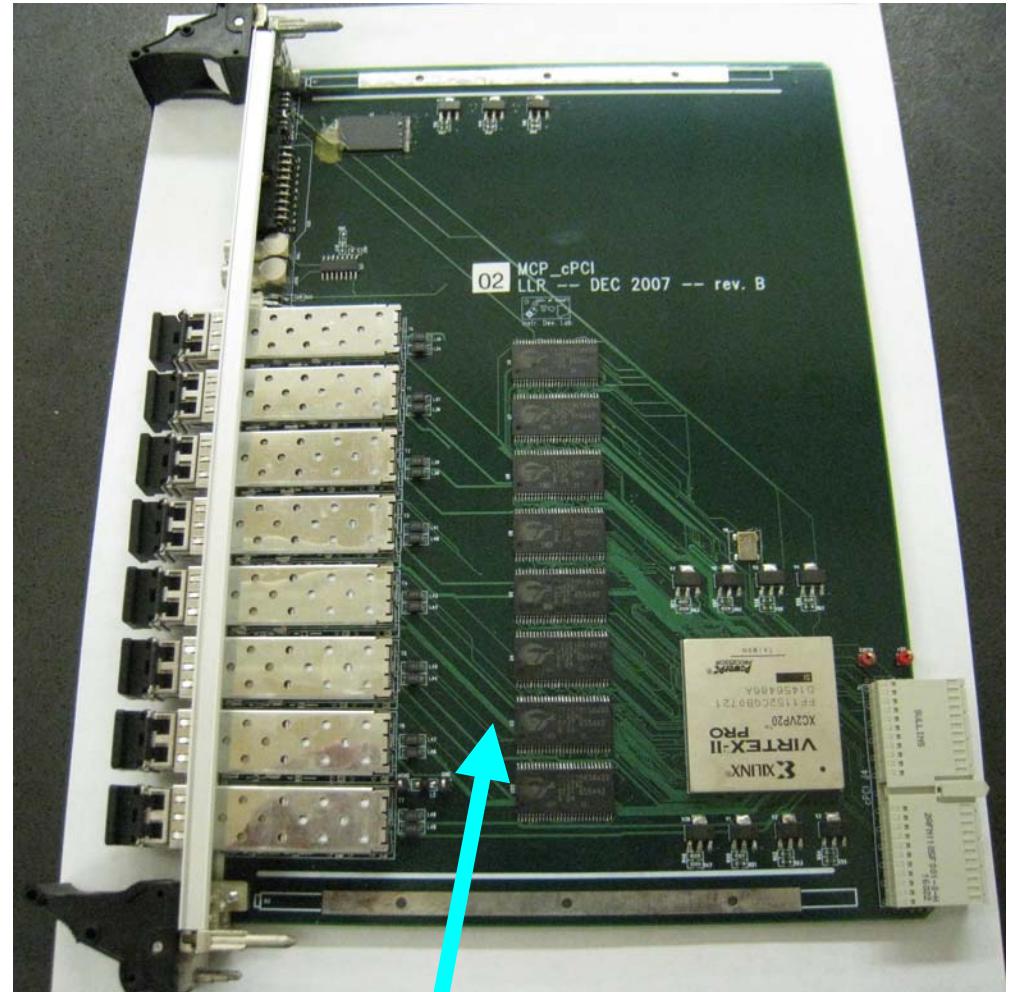
compact PCI Platform



cPCI crate

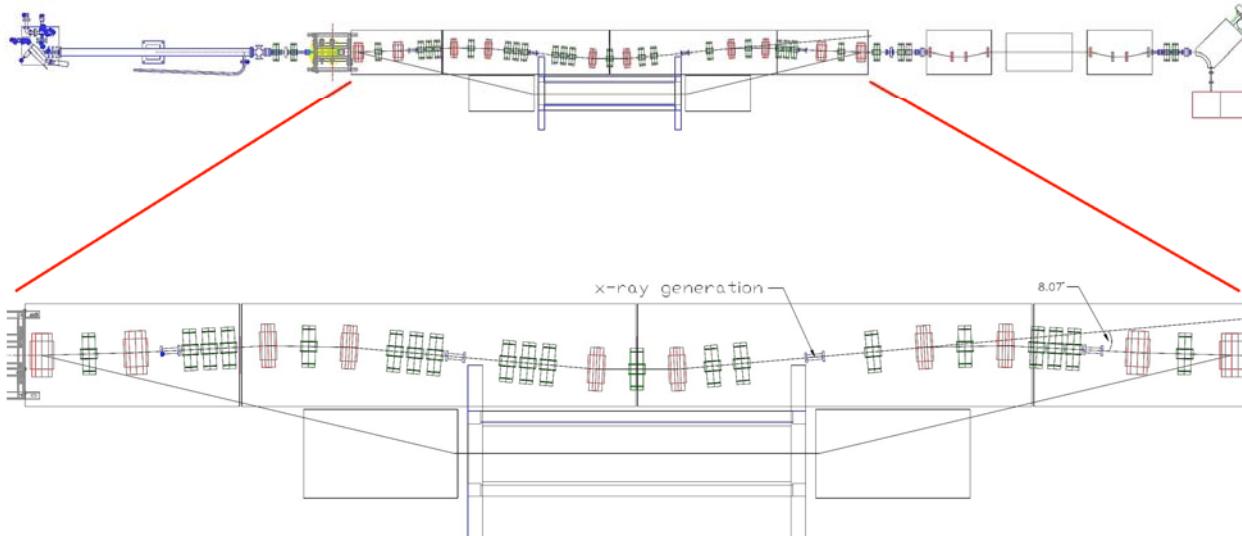
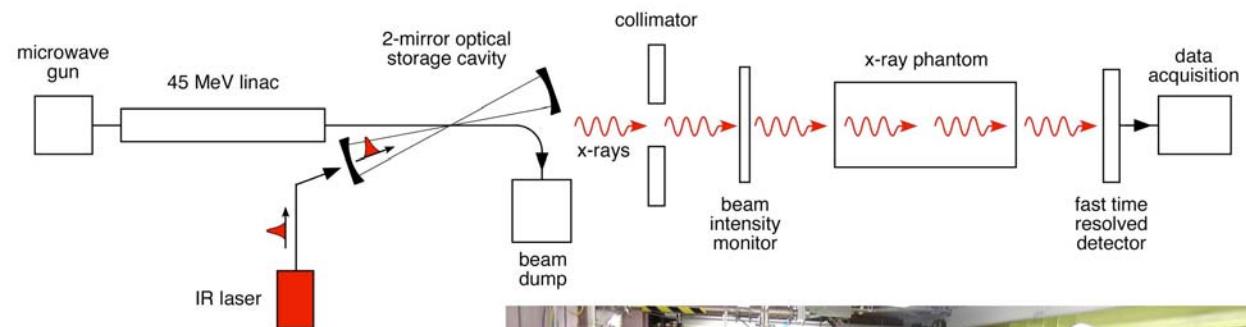
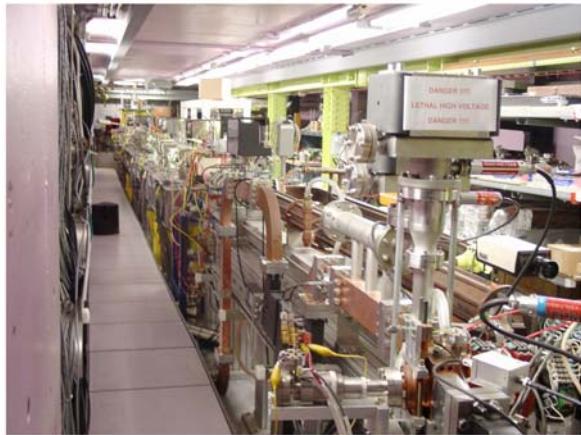


cPCI CPU



Data processing card
(example – DSP version)

Mono-chromatic x-ray Source



Future Detector Options

